

FIG. 1

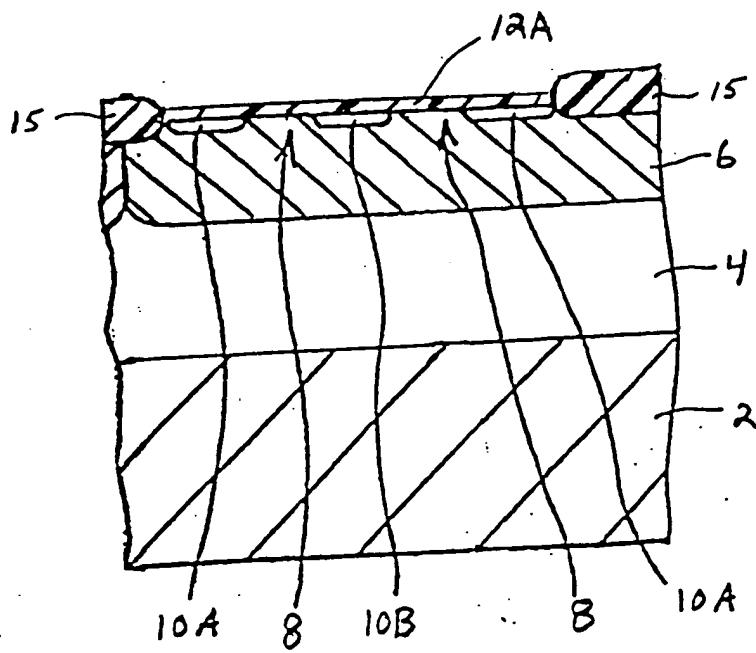


FIG. 2

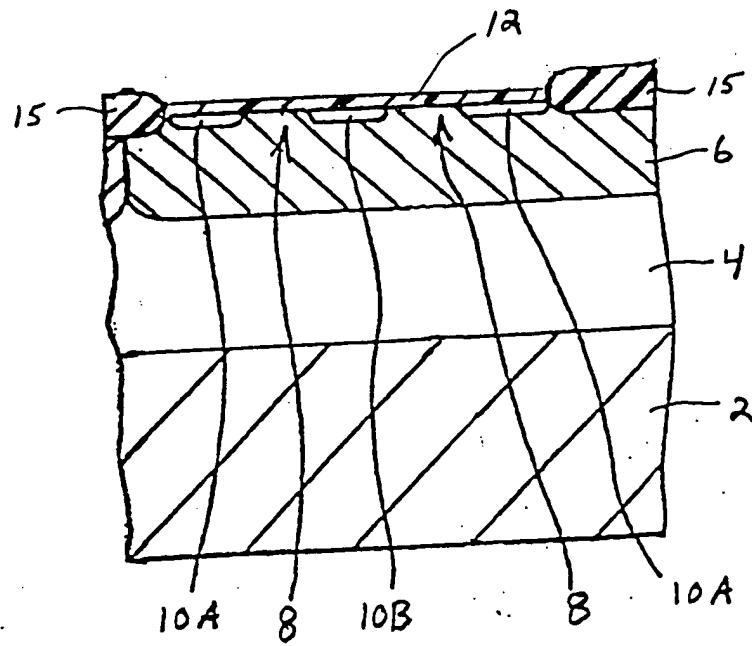


FIG. 3

6629400 2206260

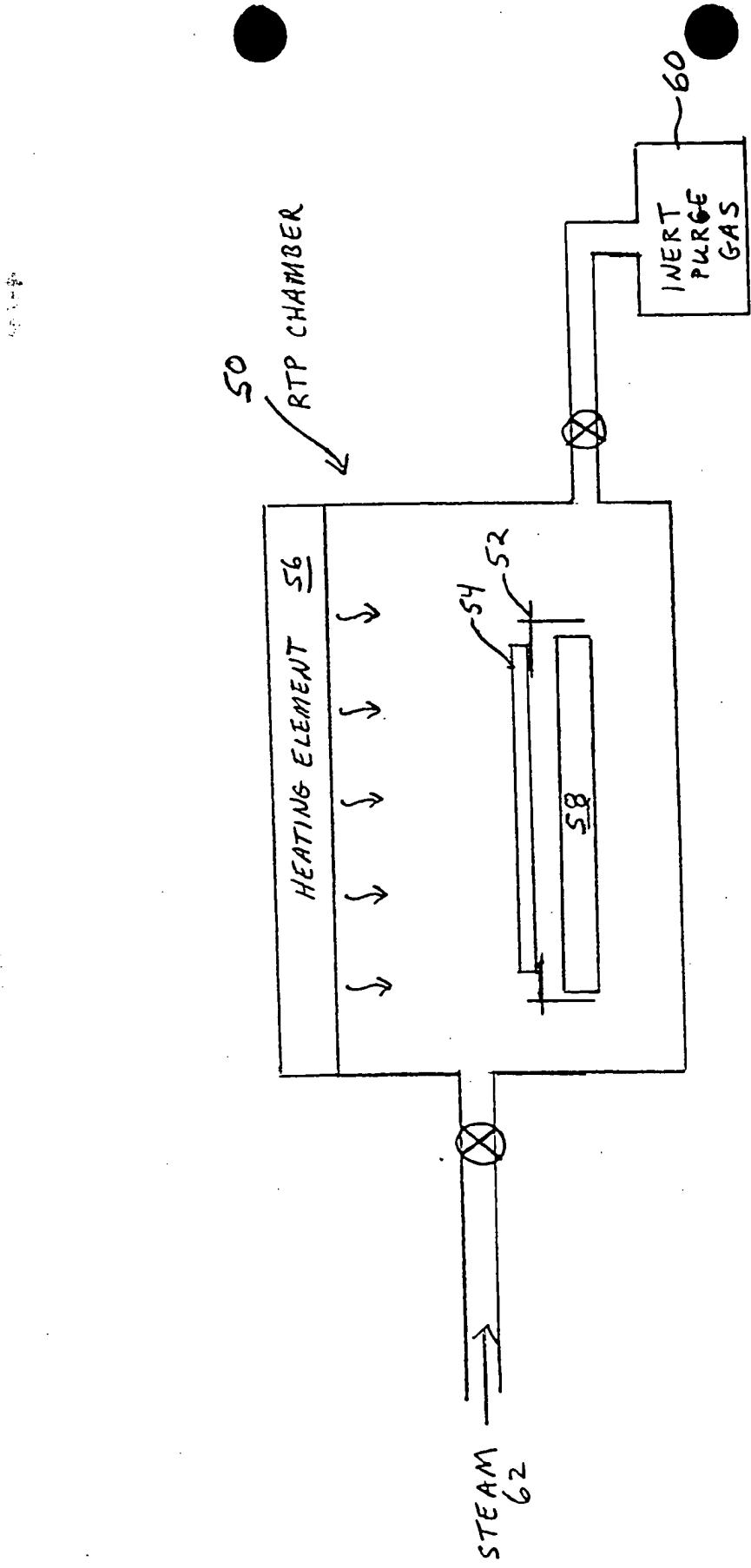


FIG. 4

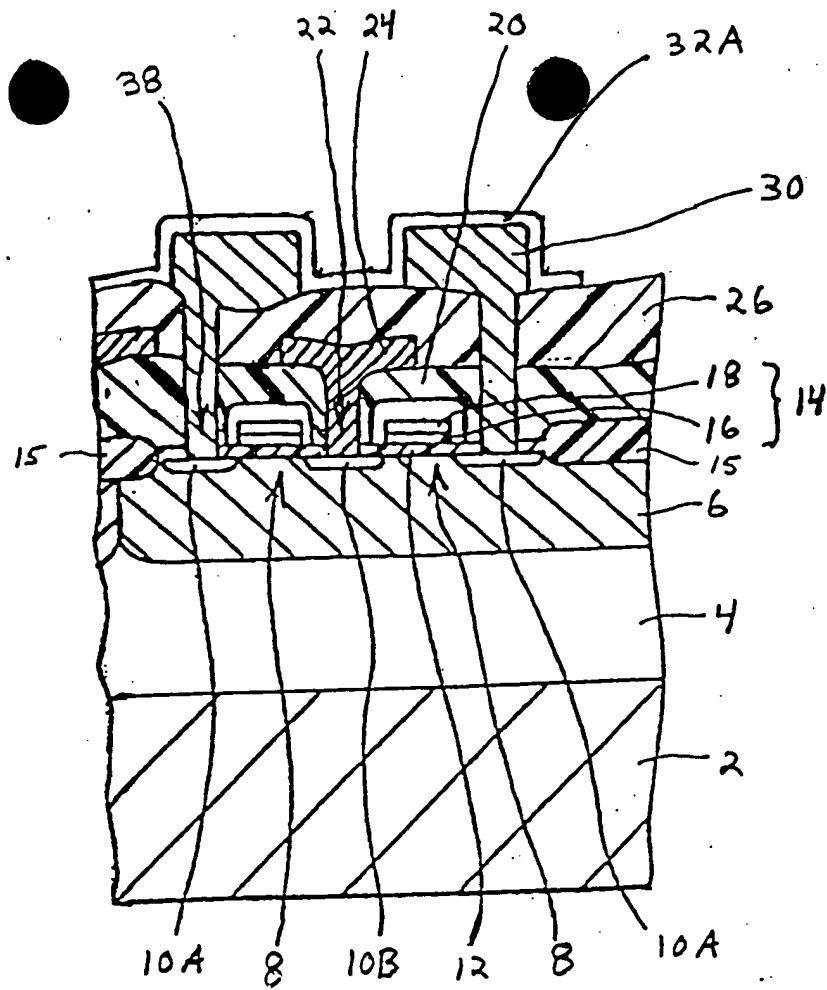


FIG. 5

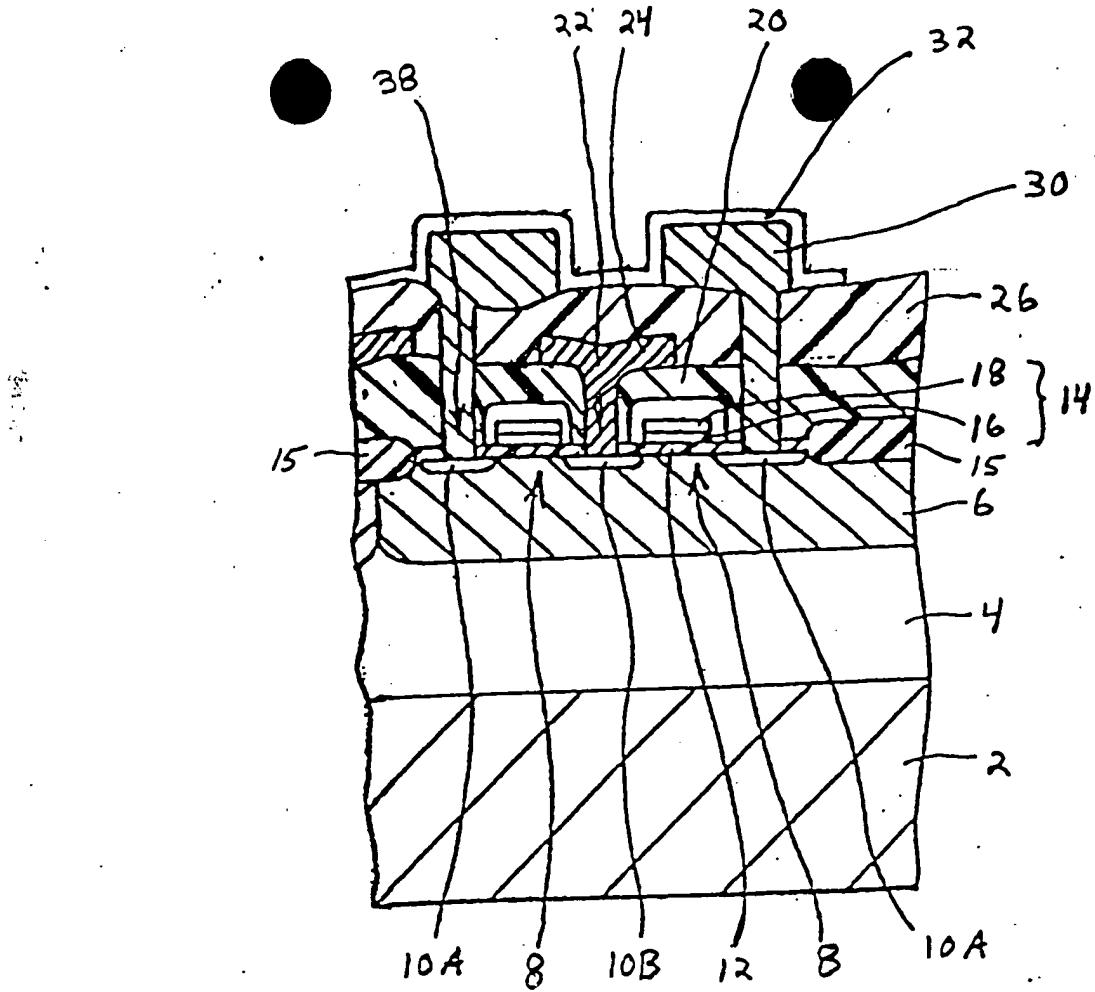


FIG. 6

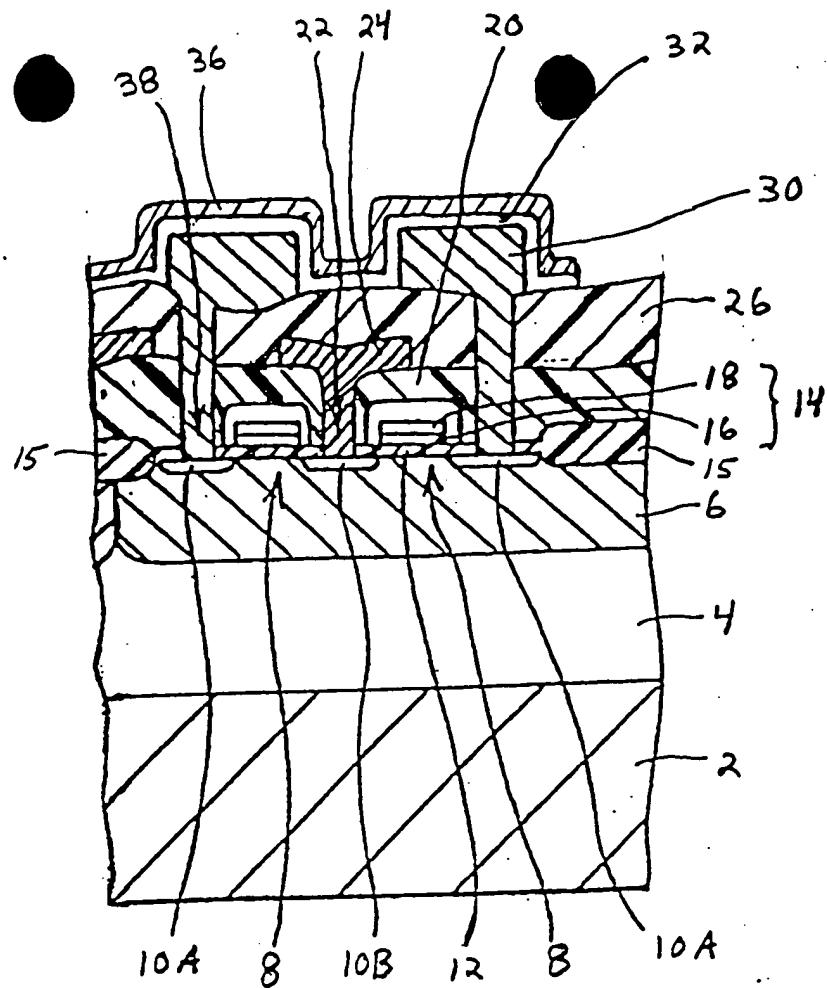


FIG. 7

DEPOSIT DIELECTRIC OR INSULATING FILM

SUBJECT THE INSULATING FILM TO A HEAT TREATMENT IN AN AMBIENT COMPRISING A STABILIZING GAS INCLUDING A GAS SELECTED FROM THE GROUP CONSISTING OF  $N_2$ ,  $O_2$ ,  $O_3$ ,  $NO$ , OR  $N_2O$

SUBJECT THE INSULATING FILM TO A WET OXIDATION IN A RAPID THERMAL PROCESS (RTP) CHAMBER

FIG. 8